

# Building a GPS Receiver for Space Lessons Learned

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## BIOGRAPHY

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## ABSTRACT

Over the past 4 years the Component Systems and Hardware branch at NASA GSFC has pursued an in-house effort to build a unique space-flight GPS receiver. This effort has resulted in the Navigator GPS receiver. Navigator's first flight opportunity will come with the STS-125 HST-SM4 mission in August 2008. This paper covers the overall hardware design for the receiver and the difficulties encountered during the transition from the breadboard design to the final flight hardware design.

Among the different lessons learned, the paper stresses the importance of selecting and verifying parts that are appropriate for space applications, as well as what happens when these parts are not accurately characterized by their datasheets. Additionally, the paper discusses what analysis needs to be performed when deciding system frequencies and filters. The presentation also covers how to prepare for thermal vacuum testing, and problems that may arise during vibration testing. It also contains what criteria should be considered when determining which

portions of a design to create in-house, and which portions to license from a third party.

Finally, the paper shows techniques which have proven to be extraordinarily helpful in debugging and analysis.

## INTRODUCTION

This design resulted from a series of developments and opportunities.

In 2001, Moreau researched and defined the capabilities which a robust space-flight GPS receiver would require [1]. This work both listed the limitations of space-flight GPS receivers available at the time and discussed techniques that could increase the maximum operational altitude of a GPS receiver to include above-the-constellation geosynchronous and highly elliptical orbits.

Dr. Moreau used the PiVoT GPS receiver, developed at GSFC, in hardware-in-the-loop simulations to provide hard data to support his analyses. Like many receivers at the time the PiVoT receiver was based on the GP2010/GPS2021 chipset. Having no frequency domain correlation capability, the receiver relied on a sequential search to acquire GPS signals.

In 2002, Winternitz [2], at NASA GSFC, mapped out a means to use the results of Psiaki's research at Cornell University [3]. This new hardware would incorporate a frequency domain correlation engine to perform weak signal acquisition. It would also move away from the commercially available correlators towards an in-house tracking design. This new design would be implemented in radiation hardened FPGAs. The goal was to achieve an acquisition and tracking threshold of 25 dB-Hz.

The design was built and debugged on a Xilinx based breadboard, provided by General Dynamics. An RF front end was constructed from a signal generator and a chain of discrete components. Using this design, the algorithm

and the system were proven. The team was successfully able to acquire and track GPS signals down to 25 dB-Hz.

In 2003, the Navigator team began working with the Magnetospheric Multiscale (MMS) Mission to develop a custom GPS receiver with an integrated S-band transceiver. The mission consists of four satellites designed to measure magnetic field variations. Each satellite needs to know its own position, as well as the distances between itself and each of the other satellites. Additionally, each satellite needs to send a science quality index to the other satellites. This combined position and messaging feature was referred to as the Inter-satellite Ranging and Alarm System (IRAS).

Because Navigator and IRAS were new technologies, MMS required that both be proven out as early as possible. In an effort to meet MMS's requirements, the Navigator team began putting together a list of parts that could meet the radiation, vibration, and power thresholds which would be seen during the life of the mission. There was the desire to expose the combined GPS and IRAS system to the space environment before the 2012 launch date, but no formal opportunity was presented at the time.

The team also began designing a system to emulate the path delays and Doppler shifts seen by the satellites as they received each others' messages. This system has become known as the PERFS (Path Emulator for RF Systems) project.

In 2005, members of the Hubble Space Telescope's fourth Servicing Mission (Hubble SM-4) offered a space flight opportunity to perform a bi-static ranging demonstration as part of the Relative Navigation Sensor (RNS) experiment. The desire was to verify if the team could use the weak signal GPS acquisition and tracking ability of the Navigator to provide relative navigation solutions between the Hubble and the space shuttle.

This would be accomplished by using the concept of bi-static ranging [4]. Using direct measurements from the GPS constellation and weak reflected signals off of the Hubble, the team plans to passively estimate the relative position of the two vehicles.

$$|\rho_{\text{diff}}| = |\rho_{\text{rel}} + \rho_{\text{HST}}| - |\rho_{\text{Direct}}|$$

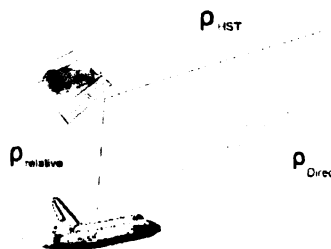


Figure 1: GPS Relative Navigation Concept

Based on pseudo-ranges  $\rho_{\text{Direct}}$  and  $\rho_{\text{HST}} + \rho_{\text{Relative}}$  from multiple visible satellites, Navigator needs to provide  $\rho_{\text{Relative}}$  for the SM-4 mission.

The launch date for Hubble SM-4 was September 2008 (and has since been moved to August 2008). This opportunity came at a perfect time. A substantial amount of research into parts selection had already been performed. Now it needed to be implemented on an accelerated schedule. Wherever possible, the team tried to make the SM-4 and GPS+IRAS designs common. This would maximize the validation of the GPS design.

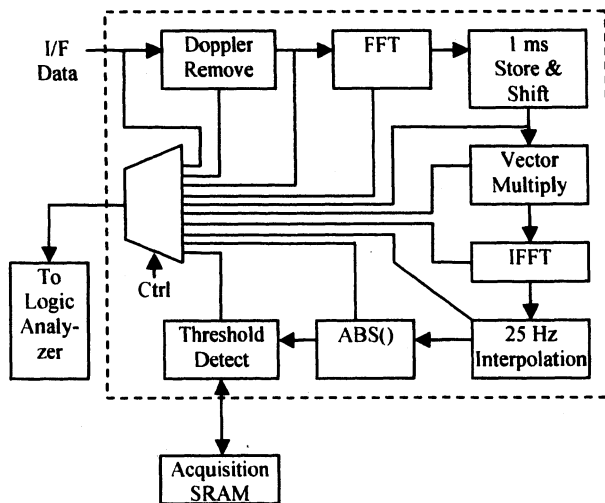
## DESIGN REQUIREMENTS

Table 1 describes some of the design requirements levied by the MMS and SM-4 missions [5]. In the cases of differing values (between the two missions), the more stringent value is used in the table.

Requirement	Threshold
Power limits	30 W
Mass	21 lbs
Power source	24 to 32 Volts DC
Vibration	14.1 G <sub>RMS</sub>
Temperature (on and off)	-30° to +60° C
Depressurization rate	0.445 (psi/sec)
Contamination (off-gassing)	1 µg/cm <sup>2</sup>
Radiation (SEU)	37 MeV-cm <sup>2</sup> /mg
Radiation (Total Dose)	100 k-rad (Si)
Physical (overall)	Should create no threat to astronauts, Space Shuttle or Telescope
GPS Accuracy (MMS)	30 m to 35 km, based on mission phase
GPS Accuracy (SM-4)	No Requirement

Table 1: Design Requirements for Navigator Receiver

In the process of verifying the mission requirements, failures were discovered. The following sections describe what is the over-all design of the system, how the team discovered each failure, how each failure was traced back



**Figure 3: Acquisition Blocks and Debugging Mux**

Several errors were discovered by observing the signals between and inside the functional blocks. These include biases in the ADCs, logical errors, rounding asymmetries, state machine errors, unexpected counter overflows, and I/O errors. A logic analyzer was used for immediate debugging and also to store data to a file for processing.

**Lesson Learned:**

Simulating VHDL is always the best method of finding bugs, however there are times when bugs only appear after a large amount of data has passed through the system. For such cases, it is important to be able to easily debug hardware in the lab using logic analyzers.

**SOLDER BRIDGES ON SRAM**

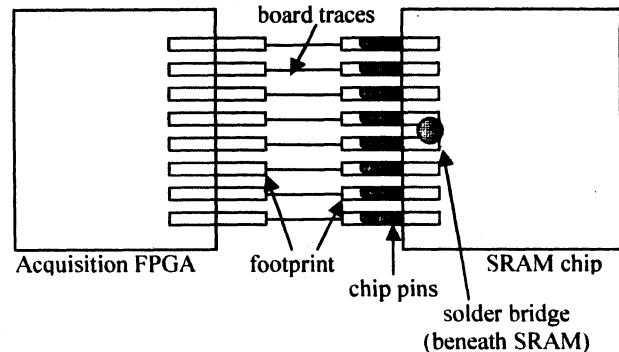
During the initial unit test of any system, the boards must be analyzed to discover any manufacturing related errors. Possible errors can include electrical shorts between power and ground, or between unrelated signals. They can include components that are not placed properly (either skew, or 90 degrees out of orientation), components that are not completely soldered down, components which are absent. The initial test also ensures that the required voltages in the system are correct and within prescribed tolerances.

Some aspects of the initial unit test can be automated, to save time and increase reliability. Some such tests are memory verification and connectivity tests. Other aspects can not be automated, such as finding the cause of a new type of failure.

On the Navigator, the acquisition SRAM connects to the acquisition FPGA and contains the coherent and non-coherent GPS correlations. Whenever power is applied, the acquisition FPGA writes a unique pattern to each address in the SRAM, and then reads it back. During the

read-back, the FPGA maintains statistics about how well the SRAM performed, such as: how many addresses failed, where was the first failure, and which data-bits failed. This gives the testing engineer a starting point in debugging most common connectivity problems.

The day that the team performed the initial unit test of the Navigator board, two sets of unrelated pins were failing. Many of the pins were address pins. This was causing data contents to be written in the wrong memory location.



**Figure 4: Location of a solder bridge**

Upon reading the statistics registers, the test engineer knew to look more closely at the pins of the SRAM. It was discovered that solder had splashed under the body of the SRAM and “bridged” (connected) two unrelated pins. This can be seen in Figure 4. Due to the location of the solder bridge, it was difficult to see unless an inspector knew that it was there. Because of the self testing mechanism, the problem was caught quickly and early in the development process.

If the problem had gone undetected, it would have caused erroneous acquisition results. Because the bridge caused two pins to be shorted together, it would likely have reduced the life span of the Acquisition FPGA which was commanding those pins.

**Lessons Learned:**

Connectivity errors are fairly common in development systems. It is generally easy to implement circuitry or software to perform basic connectivity tests. They are well worth the investment.

**POWER SPECTRAL DENSITY SPURS**

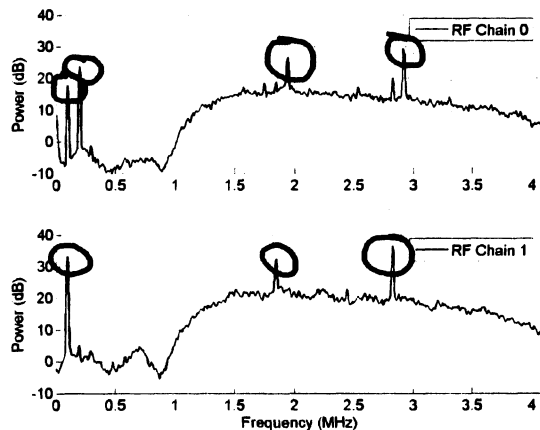
This was the most interesting problem the team faced.

The team had finished verifying the RF Daughtercard in conjunction with the strong signal functionality of the Navigator motherboard. It was time to begin verifying the weak signal acquisition mode.

We then ran several tests at 30 dB-Hz and initially were not able to acquire the signals. The first observed symptom was that the forward FFT began overflowing. This made the team think that there was a strong in-band signal that was getting to the ADC.

The team needed to isolate whether the problem was on the digital Navigator motherboard, on the analog RF Daughtercard, or in the low noise amplifier (LNA). The RF Daughtercard was disconnected and the discrete RF chain was reconnected to see if the problem was still present. The problem had gone away. The team was able to acquire the weak signal, with no problem.

The RF Daughtercard was reconnected. Digital samples of the I/F signal were taken at the Analog to Digital Converter (ADC) and stored to a file using a digital logic analyzer. When the samples were analyzed, spurs were seen in the power spectral density (PSD) plot. This showed that there was a signal that was getting into the RF or IF chain. Due to the 8.192 MHz sampling, we could only see the aliased frequency of the unwelcome signal.



**Figure 5: Location of unwanted spurs on PSD chart.**

Using an oscilloscope, the inputs to the amplifiers in the RF chain were checked for any signals above the noise floor, but none were visible. Next, beginning with the first amplifier in the RF chain (this is the amplifier which receives the RF signal from outside of the box), a team member connected the input of the amplifier to ground. The theory was that grounding the input to an amplifier should show if the in-band signal is upstream (closer to the LNA) or downstream (closer to the ADC) of the amplifier under test. If grounding the input removed the spurs from the PSD, then the in-band signal should be upstream.

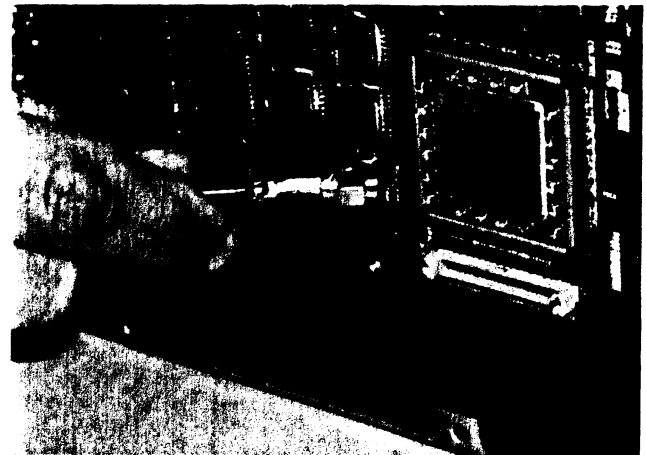
Grounding the first amplifier reduced the relative height of the peak over the noise floor, but did not eliminate it. Grounding the input to the second reduced the spur's relative height more, but also reduced the noise floor.

Grounding each amplifier's input to ground resulted in the reduction of the relative peak of the spur, until the last amplifier in the chain was grounded. At that point there was no spur and no detectable signal at all. It was determined that no single amplifier was introducing the unwelcome signal. Each one appeared to be contributing to it.

Because the spurs only occurred with the RF Daughtercard (and not with the discrete chain located on the bench top), the team wanted to determine if there was a signal radiating from the motherboard. In order to verify this, all the components would need to be turned off or removed from the motherboard. Luckily, the board design included a clock distribution tree which provided a dedicated clock signal to each component. Because of this conservative design technique, turning off each active component was an achievable goal.

Additionally, because the design was being ported and debugged, the team used sockets to hold each of the FPGAs on the board. This allowed those chips to be removed easily. For the other digital components, their clock was removed at the board's clock driver. By removing clocks to each of the digital components, one by one, and inspecting the PSD, the team was able to search for a possible aggressor. The only component which caused the PSD spurs to go away was the ColdFire microprocessor itself.

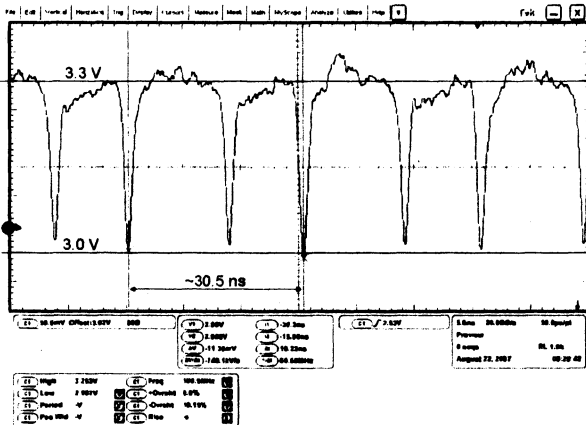
Now that the team had a suspect, they needed to characterize what aspect of the microprocessor was causing the spurs. The team's RF designer connected a coaxial cable to an amplifier and connected the output of the amplifier to a spectrum analyzer. This was done to create an "RF Sniffer." The open end of the coaxial cable was covered with kapton tape to prevent accidentally shorting any pins on the processor. The engineer then used that open end of the cable as a hand-held antenna. This antenna was passed over the processor chip to see if there were pins which were acting as aggressors.



**Figure 6: Photograph of "RF Sniffer"**

Certain signals were creating a significant amount of RF noise as seen on the spectrum analyzer. When pins on one side of the processor were probed with an oscilloscope, it was discovered that there were spurs.

The captured image in Figure 7 shows the voltage on an output pin as a function of time. This signal should be a constant 3.3 volts, however it has recurring spurs that drop down to 2.96 volts. These fast changes create noise.

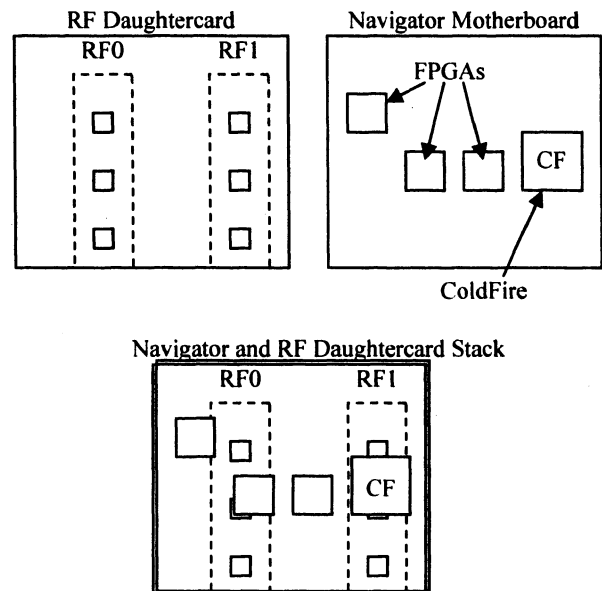


**Figure 7: Voltage Spurs on the ColdFire scan-out pins.**

The signal displayed in Figure 7 should be constantly high at 3.3 volts. The clock input to the processor is 65.536 MHz, and gets divided by two inside the processor to create a bus clock of 32.768 MHz. It appears that there are two overlapping sets of spurs, which occur at the slower clock frequency. The spurs last only 1-2 nanoseconds from the beginning of their drop to their return to the nominal 3.3 volts. Each spur seen has a magnitude of approximately 0.3 volts.

The peaks were occurring at a frequency of approximately 65.536 MHz. The team observed the harmonics of this frequency on the spectrum analyzer. The 24<sup>th</sup> harmonic of this frequency is 1.57286 GHz, and the L1 C/A code signal is located at 1.57542 GHz. The signals are separated by only 2.56 MHz. While the RF filter's pass band was only 2 MHz wide, the cutoff was not sharp enough to attenuate the emitted harmonic. This harmonic affected each of the amplifiers located before the mixer. Once the incoming signal is mixed down to 35.42 MHz, it is no longer susceptible to the aggressor.

Physical separation also affects the magnitude of interference. As seen Figure 8, only the RF1 chain which was located physically "above" the processor was seriously affected. Even though RF0 was located above several FPGAs, it was only slightly affected by the interference.



**Figure 8: Diagram of relative location of components.**

So how was the aggressor generated?

The scan-out signal is part of a twelve bit scan bus output used for factory boundary-scan testing. The processor uses scan-in and scan-out signals to test internal functions, and verify transactions. Once the processor is deemed "good," the scan bits are no longer needed. There are several instructions the manufacturer recommends that the user perform to keep them disabled. According to the datasheet, the user should disable the signals through software. The user is also instructed to leave the output pins unconnected. Both of these instructions were followed.

The team contacted the manufacturer to ask if this unwelcomed spur was a common occurrence, and determine if there was way to mitigate the problem. The manufacturer was able to successfully recreate the conditions in their lab, and also saw the same symptoms on their processor's scan-out pins. Even though they were able to study the problem, they were unable to provide a solution to removed the spurs.

### Mitigation

Although there was no ready solution to remove the jamming signal, a way had to be found to mitigate the problem. The RF chain had an excess of gain. Each chain had approximately 50 dB of onboard amplification. The rest was off board (located in the antenna's LNA). The gain was needed to implement an Automatic Gain Control (AGC) circuit, which could attenuate any excess gain using digital step attenuators (DSAs). Because each amplifier was allowing the signal to get into the chain, one was removed. This reduced the gain to 37 dB. While

it reduced the dynamic range of the AGC, it did not take away from the system as a whole.

Additionally unshielded passive components on the RF daughtercard were swapped with shielded versions, if available. This improved the magnitude of the jamming frequency, as shown below.

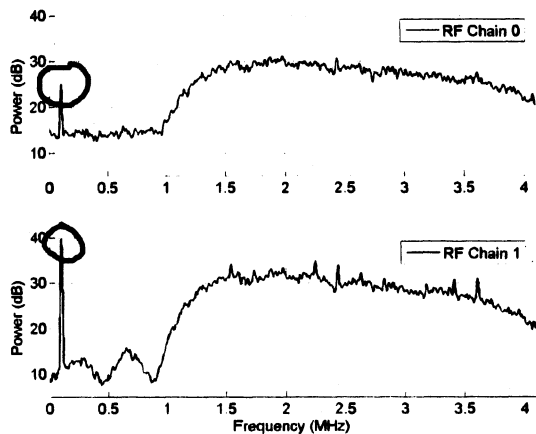


Figure 9: Location of mitigated spurs in PSD chart.

As a result of the mitigation techniques, the LHCP chain (RF Chain 0 - which performs weak signal acquisition) no longer had any spurs above or in the pass band centered at 2.652 MHz. Only one spur was located below the noise floor, but it did not degrade the weak signal acquisition. The RHCP chain (RF Chain 1) still had one spur above the noise floor. Because that chain was only performing fast acquisition, its performance also was not degraded.

#### Lesson Learned:

When there is a substantial amount of gain in the design, be sure to look beyond the first few harmonics of your frequencies. Perform a complete frequency analysis of the system. Limit the number of clock frequencies in your system, and ensure that harmonics of base frequencies will not appear near or in the pass band of the receiver's RF chain. If it appears that frequencies may be close to one another, discuss mitigation plans ahead of time.

Ensure that the outputs of any digital circuit are set to low slew (the slowest transition rate). Also ensure that high speed digital signals are properly terminated. Un-terminated high slew signals produce reflections, and cause noise on power and ground lines.

#### OSCILLATOR VIBRATION FAILURE

Transporting any payload into orbit puts a tremendous amount of physical stress on a system. It is imperative to ensure that space design can survive the conditions experienced during a launch. In space, a damaged piece of

equipment is often no more useful than a piece of bent metal. Therefore, every component of the final design must be exposed to launch-like accelerations while still on the ground.

In October 2007, the team prepared the completed space flight Navigator GPS Receiver for vibration testing. The goal was to shake the design while it was powered on and operational. A GPS signal generator ran an orbital simulation and sent analog RF data through a coaxial cable to the receiver. A power supply provided the 28 volts DC necessary for the design. The Navigator GPS receiver generated telemetry data through a high speed serial RS644 connection. This serial connection was the only means to monitor the functionality of the system while under test.

The receiver was mounted to a Ling Dynamic Systems' Model 730-335 vibration system. This shaker table consists of coiled wire, a magnet, a very powerful cooling fan, and a PC interface. It behaves as a large low frequency vertical speaker. The unit is capable of generating 75  $G_{PEAK}$  of acceleration, to a vertical displacement of up to 2.0 inches (peak to peak). The vibration frequency can range from DC to 3 kHz. It can place a maximum force of 8800N (2000 lbf). There are different table adapters to allow space instruments to be shaken in the X, Y or Z dimensions. The PC controls the acceleration profile to which a system is exposed.

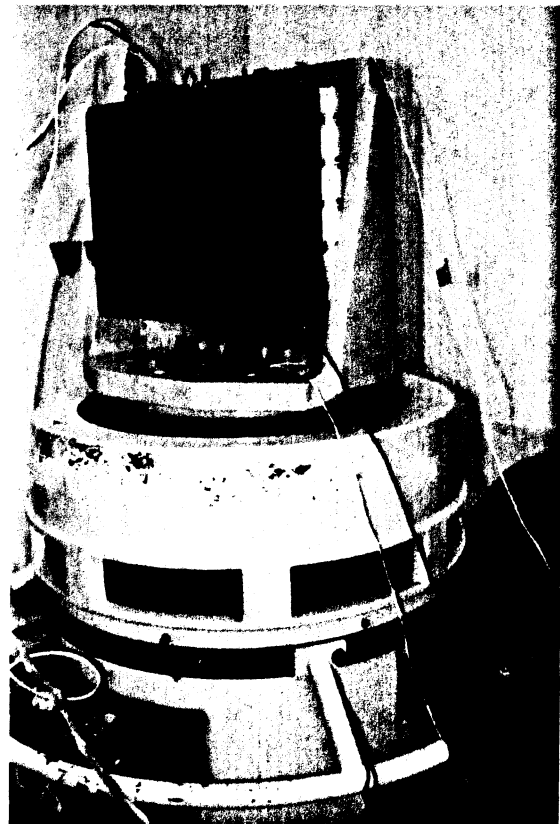


Figure 10: Navigator GPS tested on shaker table.

The Navigator space flight unit was exposed to three difference profiles: sine sweep, sine burst, and random vibration. The random vibration consisted of three different levels: 25%, 50%, and 100% of the required 14.1 G<sub>RMS</sub>.

The telemetry data was monitored to verify nominal operation of the receiver throughout the test. The following table describes the outcome of the test in the X dimension:

Test	Result
Sine Sweep (.25 G)	Pass
Sine Burst (22 G)	Pass
Random Vibration (25%)	Pass
Random Vibration (50%)	Pass
Random Vibration (100%)	Loss of telemetry

**Table 2: Results of Vibration Tests**

When the telemetry was lost from the receiver, the test was discontinued. No further tests were performed that day. The system was returned to a Electro-static Discharge (ESD) controlled space-flight qualified lab and was disassembled for inspection.

It was discovered that the system's Oven Controlled Crystal Oscillator (OCXO) had an interior mechanical failure. When the part was removed from the board, an engineer stated "when you shook the OCXO, it sounded like a baby rattle."

The oscillator was picked because its family was listed as space flight qualified. The acceleration rating on the part was 20 G<sub>RMS</sub>.

So why did the part fail?

Two engineers were responsible for ordering and qualifying the OCXO. Traditionally, this is the responsibility of a parts engineer. However, because of budgetary restrictions, no parts engineer had been assigned to the team. During the post failure analysis, both engineers were interviewed. They picked the part due to the space rating and due to its frequency stability which were claimed in the datasheet. The engineers wanted to verify that the OCXO performed as expected. So they contacted the manufacturer, ordered five units and specified the frequency as 65.536 MHz.

The data sheet claimed the following properties:

OCXO	220 221 Series
Radiation Hardness	60 Krads (Si) TID
Pyroshock tested	Yes
Vibration	20 G <sub>RMS</sub> (Minimum)
Shock test	1000 G peak
Lead Time	18-22 weeks
Warranty	Two Year

**Table 3: OCXO Datasheet**

An additional information flyer provided the following information about the physical dimensions:

OCXO	220 221 Series
Package Type	16 pin DIP
Pin Type	Through Hole (220) Surface Mount (221)
Physical Dimensions	.975"L x .800"W x .500"H
Warm Up Time	Less than 5 minutes
Applications	GPS Receivers

**Table 4: OCXO Second Datasheet**

Apparently the two datasheets can refer to different parts (a space-flight part and a commercial equivalent) based on a suffix to the family part. This information was not in the datasheet. In order to specify whether the part is a space flight grade OCXO, the vibration and radiation grades must be specified. Both versions have the same family number.

Although engineers A and B were evaluating the oscillator, engineer A (who was the one who actually ordered the part) believed that they were only ordering the part to evaluate it. Because of this, he did not include any space characteristics in the list of requirements. Neither engineer knew that there were two versions of the oscillator.

When the part arrived, engineer A verified that it functioned properly with the system. It provided an appropriate amount of frequency stability. When engineer B received the properly functioning part, he assumed that it was space-rated, as described in the datasheet. In reality the received part was a pin-compatible commercial equivalent to the space-flight part.

Upon discovering the error, the team ordered the correct space flight qualified OCXOs. As a result of how late in the development process the failure was discovered, the manufacturer accelerated the assembly and the shipping of the parts. The Navigator team was then able to successfully perform the vibration test of the system.

Lessons Learned:

1. Large teams generally consist of smaller specialized groups. Ensure everyone on the team knows what the development plan will be for the entire system.

2. Be careful when using special-order components. Try to evaluate the actual part which will be used. If parts are being evaluated against related parts, ensure that everyone knows when the transition will be made to the final part. Don't forget to verify the final part.

3. If the design is complex and the budget allows for it, have a dedicated parts engineer to verify that *every component* in the system meets the same minimum requirements. Create tables that show which parts have met the requirements, and which haven't.

### RF FPGA VIBRATION FAILURE

After the OCXO failure, further system testing and inspection was performed. This inspection revealed that the FPGA on the RF Daughtercard also had several failures. The pins had broken near the point where they connect to the top of the FPGA. These breaks appear as a clear separation from the connection point to the FPGA.



Figure 11: Photo of the pin broken

The FPGA was an Actel RT32SXA space rated FPGA, containing 208 pins running 52 on each edge of the chip. This chip had a RT prefix to the part number, ensuring that there is no ambiguity about its space rating. Even with this rating, it was discovered that 32 pins had broken.

So why did the part fail?

First, a brief history on the component: This FPGA is one that can generate a fair amount of heat during use. Since convection cooling is not an option in space (because there is no air to move), the only way to cool the part is through conductive cooling (taking the heat from the chip and passing it to the circuit board by physical contact).

In order to improve the conductive cooling, the manufacturer placed a thermal plate on the bottom of the FPGA. This plate is designed to quickly remove the heat from the body of the chip. Not only is the plate thermally conductive, but it is also *electrically conductive*. This is a

well understood way of removing heat, but (if it isn't handled well) could electrically connect many unrelated signals on the board. Therefore, a gel must be used which is a good conductor of heat, and also an electrical insulator.

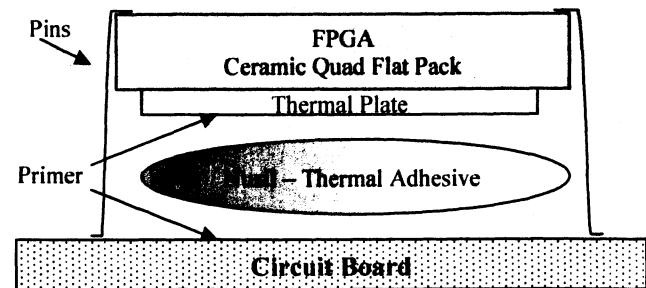


Figure 12: Location of Nusil under FPGA

Board designers began using a thermal adhesive called Nusil. Nusil has the appropriate electrical and thermal properties needed. An added benefit of this thermal adhesive is that after it is in place for 24 hours, it alleviates stress during vibration by acting as a strong glue.

There are two requirements to achieve this benefit. The first is to place a primer on the bottom of the chip and on the circuit board. Without the primer, the thermal adhesive is not able to stick to anything. The second, sufficient Nusil must be used to cover 80%-90% of the bottom area of the FPGA.

During post-failure analysis, it was discovered that primer was not placed on the FPGA or the board. Secondly, Nusil only covered 40% of the area under the part. Upon further analysis, it was discovered that there was not enough documentation. A technician who was not familiar with the process of using primer in these situation assembled the board. Finally, due to accelerated schedules, the Board left the lab with only a minor inspection.

### Lessons Learned

Don't let aggressive schedules cause your team to overlook details. Ensure that any special procedures are well documented. Engineers who are familiar with techniques have tendencies to forget details. Documentation is even more important, when involving engineers who are unfamiliar with the processes.

### RF AMPLIFIERS FOOTPRINT FAILURE

During the unit test of the RF Daughtercard, the RF engineer tested the resistance between the power plane and the ground plane. His equipment measured it as a short. He needed to find out what was causing the



electrical connection between the two independent voltages.

During his testing, he was measuring an unplaced amplifier. This amplifier, which was not on the board, also measured a short between its power pin and its ground pin. Initially, he believed that it was a bad part. After measuring three identical parts, he realized that all had the same internal short. He then unsoldered this family of parts from the RF Daughtercard. There was no longer a short on the board.

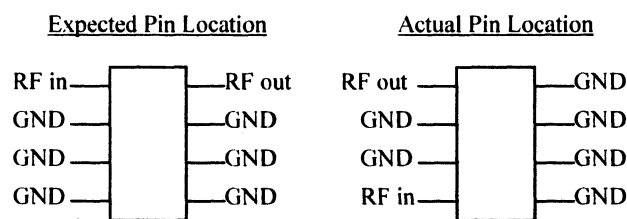
So why did this family of parts fail?

These parts were a semi-custom order. The dies were commercial silicon, which were up-screened for the temperature specifications of the mission. These silicon dies were then placed in space flight packages.

During the ordering process, the point of contact at the company provided the technical information for the family. In an email, he gave the RF designer a datasheet of a similar amplifier and informed the designer that the company would make the electrical and mechanical design of the new part to be the same as this related amplifier.

He was apparently unaware that it would be different.

Of the eight pins on the amplifier, the Power (which is also RF-Out), the RF-In and the ground pins were at locations other than what was described in the datasheet.



**Figure 13: Pin locations of the supplied amplifier.**

The RF engineer contacted the company to determine what had happened. In an emailed response, the point of contact acknowledged the company had changed the pin locations without informing him, but he did not know what was the rationale. He offered to replace any damaged parts.

To verify the correct pin locations, the team needed to “dead bug” the amplifier. Dead bugging a part generally means that the component is glued to the board with its pins (the legs) up in the air. Wires are manually soldered onto these dead bug legs.

After verifying the correct pin location, the team needed to refabricate the printed circuit board with the correct footprint of the amplifier.

#### Lessons Learned

When ordering custom parts, allow enough time to test and fix any unforeseen problems. If possible, it is very helpful to test the custom part independently on a breadboard or wire-wrap board, before you commit your printed circuit board to that design.

#### SUMMARY

New technologies drive our industry. When implementing these new designs, we know that there is a tremendous amount of validation and debugging to ensure a stable product. There are many problems that can be experienced:

First of all, the most important and recurrent theme in this paper has been the need to validate that each component in the system behaves as the designer intended it. Identifying higher risk components early, and allowing time to ensure their characteristics, is an important responsibility. Sufficient testing should also be performed on the integrated product to verify that the components do not create any unwanted side effects to other portions of the system.

Secondly, we have found that the effort invested (early in the design process) into making testing easier, offers time savings throughout the entire development and debugging process. Ensure that the designers know what tools they will have available to them during the development portion (such as logic and spectrum analyzers) so that they may take advantage of those tool when creating their design.

Third, when dealing with suppliers of intellectual property, remember that the goals of the supplier may not be the same as yours. If they are unable to meet your needs, it can be very beneficial to either go to another supplier, or build it in-house. You may also find a member of your team to design the item instead, as long as that member understands the functionality you wish to purchase.

Finally, there are certain challenges which can be predicted in a development cycle, and some which can not. It is necessary to incorporate extra time into development schedules. Designs may not be error free on the first attempt. Give your team some amount of time to fix these unexpected problems.

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## **REFERENCES**

- 1) Moreau, M.C., "GPS Receiver Architecture for Autonomous Navigation in High Earth Orbits", Department of Aerospace Engineering Sciences, University of Colorado 2001
- 2) Winternitz, L.M., Moreau, M.C., Boegner, G.J., Sirotzky, S.L., "Navigator GPS Receiver for Fast Acquisition and Weak Signal Space Applications" Proceedings of the Institute of Navigation GNSS 2004 Conference, September 2004
- 3) Psiaki, M. L. "Block Acquisition of Weak GPS Signals in a Software Receiver," Proceedings of the Institute of Navigation GPS 2001 Conference, Salt Lake City, Utah, September 2001
- 4) I. Cohen, "Relative Navigation for Hubble Servicing Mission Using Reflected GPS Signals", Master's Thesis, University of Maryland at College Park, MD, 2007
- 5) General Environmental Verification Standard, NASA Goddard Space Flight Center, Greenbelt MD, April 2004